

NEWS RELEASE

STABLCOR TECHNOLOGY, INC. AWARDED PROCESS PATENT IN JAPAN

Huntington Beach, CA - January 28, 2014 – StablcOR Technology, Inc. is pleased to announce the acceptance of **STABLCOR®** processing Technology by the Japanese Patent Office. The acceptance of **“MANUFACTURING PROCESS: HOW TO CONSTRUCT CONSTRAINING CORE MATERIAL INTO PRINTING WIRING BOARD”** further strengthens our portfolio within Asia and our commitment to enhance the **STABLCOR®** Technology within Japan, and abroad.

About StablcOR Technology, Inc.

StablcOR Technology, Inc. is an Intellectual Property company and the only provider of **STABLCOR®**, a thermally and electrically conductive carbon composite material which, when incorporated within printed circuit boards and substrates, controls heat, thermal expansion, increases rigidity and strength, with no weight premium. The patented laminate and processes to incorporate **STABLCOR®** into printed circuit boards and substrates provides the electronic industry a cost efficient technology to produce smaller electronic products while eliminating the thermal, mechanical, and reliability concerns that currently challenge the semiconductor industry. For more information about **STABLCOR®** visit our website at www.stablcOR.com.

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